



Examiner Initial	Item No.	Document No.	Date	Name	Class	Subclass
EX	1US	3,642,526	Feb-72	Itoh, et al.		
	2US	3,784,402	Jan-74	Reedy, Jr.		
	3US	4,368,098	Jan-83	Manasevit		
	4US	4,765,845	Aug-88	Takada, et al.		
	5US	4,983,535	Jan-91	Blanchard		
	6US	4,996,584	Feb-91	Young, et al.		
	7US	5,036,017	Jul-91	Noda		
	8US	5,084,417	Jan-92	Joshi, et al.		
	9US	5,135,808	Aug-92	Kimock, et al.		
	10US	5,221,853	Jun-93	Joshi, et al.		
	11US	5,225,561	Jul-93	Kirlin et al.		
	12US	5,232,872	Aug-93	Ohba		
	13US	5,280,012	Jan-94	Kirlin et al.		
	14US	5,352,917	Oct-94	Ohmi		
	15US	5,400,739	Mar-95	Kao et al.		
	16US	5,453,494	Sep-95	Kirlin et al.		
	17US	5,625,204	Apr-97	Kao et al.		
	18US	5,920,080	Jul-99	Jones		
	19US	5,932,006	Aug-99	Santiago et al.		
	20US	5,955,785	Sep-99	Gardner et al.		
	21US	5,965,810	Oct-99	Holbrook		
	22US	5,968,847	Oct-99	Ye et al.		
	23US	6,077,775	Jun-00	Stumborg et al.		
	24US	6,120,844	Sep-00	Chen et al.		
	25US	6,139,905	Oct-00	Chen et al.		
	26US	6,144,050	Nov-00	Stumborg et al.		
	27US					
	28US					
	29US					
	30US					
	31US					
	32US					
	33US					
	34US					
	35US					
	36US					

EXAMINER:

DATE CONSIDERED:

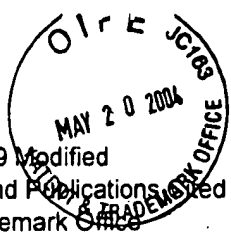
8/11/2004
~~11/20/2004~~



Examiner Initial	Item No.	Foreign Patent Document No.	Date	Country	Translation (Yes/No)
EL	1F	WO-00/11731	3/1/2000	PCT	
EL	2F	JP 402143531-A	6/1/1990	Japan	
EL	3F	JP 6-164004	6/10/1994	Japan	
	4F				
	5F				
	6F				
	7F				
	8F				
	9F				
	10F				
	11F				
	12F				
	13F				
	14F				
	15F				
	16F				
	17F				
	18F				
	19F				
	20F				
	21F				
	22F				
	23F				
	24F				
	25F				
	26F				
	27F				
	28F				
	29F				
	30F				
	31F				
	32F				
	33F				
	34F				
	35F				
	36F				
	37F				
	38F				
	39F				
	40F				
	41F				
	42F				
	43F				
	44F				
	45F				
	46F				


EXAMINER:

8/11/2004
~~11/30/2004~~
DATE CONSIDERED:



FORM PTO-1449 Modified
List of Patents and Publications Filed by Applicant
U.S. Patent Trademark Office

Page 1 (Other Documents)

U.S. App. No.: 09/853,925
Filed: May 9, 2001
Group: 2813
Applicant: Chu et al
Docket No.: NSWC-1008US

Examiner Initial	Item No.	Other Documents (Including Author, Title, Date, Location and Pertinent Pages)
ER	10D	Vogt et al., "Dielectric Barriers for Cu Metallization Systems", <u>Materials for Advanced Metallization</u> , MAM '97, pp 51-52, 1998
ER	20D	"Electrically reprogrammable FAMOS structure," IBM Technical Disclosure Bulletin, 3/1/73, Vol. 15, Issue 10, pp. 3264-3266
ER	30D	Murarka - "Multilevel interconnections for ULSI and GSI era," Materials Science and Engineering, R19 (1997), pp. 87-151
ER	40D	Murarka - "Diffusion Barriers - for Thin Film Metallizations," Defect and Diffusion Forum, Vol. 59 (1998), pp. 99-110
	50D	
	60D	
	70D	
	80D	
	90D	
	100D	
	110D	
	120D	
	130D	
	140D	
	150D	
	160D	
	170D	
	180D	
	190D	
	200D	
	210D	
	220D	
	230D	
	240D	
	250D	
	260D	
	270D	
	280D	
	290D	
	300D	
	310D	
	320D	
	330D	
	340D	
	350D	
	360D	
	370D	
	380D	
	390D	
	400D	
	410D	

EXAMINER:

8/11/2004
~~11/30/2004~~
DATE CONSIDERED: